

IBIS EVOLUTION
(IBIS, PACKAGE, ELECTRICAL BOARD DESCRIPTION, EMI, SSO, ALGORITHMIC MODELING INTERFACE)
Bob Ross, July 25, 2006, updated September 14, 2007, September 8, 2013, April 20, 2014, July 31, 2015

HEADER SECTION (.ibs, .pkg, .ebd)

Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
[IBIS Ver]	[Copyright]				
[Comment Char] (re-defined anywhere in file)					
[File Name]					
[File Rev]					
[Date]					
[Source]					
[Notes]					
[Disclaimer]					

TOP-LEVEL KEYWORDS (with END Keywords)

Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
[Component]	[Define Package Model] (.ibs, .pkg)	[Model Selector]	[External Circuit]	[Test Load] (defined under [Model] in 4.2)	
[Model]	[End Package Model] (.ibs, .pkg)	[Submodel]	[End External Circuit]	[Test Data] (defined under [Test Load] in 4.2)	
[End]	[End] (.pkg)	[Begin Board Description] (.ebd)			
		[End Board Description] (.ebd)			
		[End] (.ebd)			

[Component] PINOUT AND PACKAGE SECTION

Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
[Component]	[Pin Mapping]	[Series Pin Mapping]	[Alternate Package Models]	[Begin EMI Component]	[Repeater Pin]
[Manufacturer]	[Diff Pin]	[Series Switch Groups]	[End Alternate Package Models]	[End EMI Component]	
[Package]	[Package Model]		[Node Declarations]		
[Pin]			[End Node Declarations]		
			[Circuit Call]		
			[End Circuit Call]		

[Model] SECTION

Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
[Model]	[Temperature Range]	[Model Spec]	[Receiver Thresholds]	[Begin EMI Model]	[Initial Delay]*
[Voltage Range]	[Pullup Reference]	[Driver Schedule]	[External Reference]	[End EMI Model]	
[Pulldown]	[Pulldown Reference]	[TTgnd]	[Test Data]	[Algorithmic Model]	
[Pullup]	[POWER Clamp Reference]	[TTpower]	[Rising Waveform Near]	[End Algorithmic Model]	
[GND Clamp]	[GND Clamp Reference]	[On]	[Falling Waveform Near]	[ISSO PU]	
[POWER Clamp]	[Rgnd]	[Off]	[Rising Waveform Far]	[ISSO PD]	
[Ramp]	[Rpower]	[R Series]	[Falling Waveform Far]	[Composite Current] (under [Rising Waveform])	
	[Rac]	[L Series]	[Diff Rising Waveform Near]	[Composite Current] (under Falling Waveform))	
	[Cac]	[Rl Series]	[Diff Falling Waveform Near]	[C Comp Corner]	
	[Rising Waveform]	[C Series]	[Diff Rising Waveform Far]		
	[Falling Waveform]	[Lc Series]	[Diff Falling Waveform Far]		
		[Rc Series]	[Test Load]		
		[Series Current]	[External Model]		

		[Series MOSFET]	[End External Model]		
		[Add Submodel]			
[Submodel] SECTION					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
		[Submodel]			[Initial Delay]*
		[Pullup] (1.1)			
		[Pulldown] (1.1)			
		[GND Clamp] (1.1)			
		[POWER Clamp] (1.1)			
		[Ramp] (1.1)			
		[Rising Waveform] (2.1)			
		[Falling Waveform] (2.1)			
		[Submodel Spec]			
		[GND Pulse Table]			
		[POWER Pulse Table]			
PACKAGE MODEL DEFINITION (within .ibs or as .pkg)					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
	[Define Package Model]	[Number Of Sections]			[Merged Pins]*
	[Manufacturer] (1.1)				
	[OEM]				
	[Description]				
	[Number Of Pins]				
	[Pin Numbers]				
	[Model Data]				
	[End Model Data]				
	[Resistance Matrix]				
	[Inductance Matrix]				
	[Capacitance Matrix]				
	[Row]				
	[Bandwidth]				
	[End Package Model]				
ELECTRICAL BOARD DESCRIPTION (.ebd)					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
		[Begin Board Description]			
		[Manufacturer] (1.1)			
		[Number Of Pins]			
		[Pin List]			
		[Path Description]			
		[Reference Designator Map]			
		[End Board Description]			
[Model] SUBPARAMETERS					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*/6.1*
Polarity	Cref		C_comp_pullup		
Enable	Rref		C_comp_pulldown		
Model_type	Vref		C_comp_power_clamp		
C_comp	Vmeas		C_comp_gnd_clamp		
Vinh			Rref_diff		
Vinl			Cref_diff		
Model_type SELECTIONS					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
Input	Open_sink	3-state_ECL	Input_diff		
Output	Open_source	Series	Output_diff		
3-state	I/O_open_drain	Series_switch	3-state_diff		
Open_drain	I/O_open_sink		I/O_diff		
I/O	I/O_open_source				
	Input_ECL				

	Output_ECL				
	I/O_ECL				
	Terminator				
[Model Spec] SUBPARAMETERS					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
		Vinh	Cref	Weak_R	
		Vinl	Rref	Weak_I	
		Vinh+	Vref	Weak_V	
		Vinh-	Cref_rising	D_overshoot_area_h	
		Vinl+	Cref_falling	D_overshoot_area_l	
		Vinl-	Rref_rising	D_overshoot_ampl_h	
		S_overshoot_high	Rref_falling	D_overshoot_ampl_l	
		S_overshoot_low	Vref_rising		
		D_overshoot_high	Vref_falling		
		D_overshoot_low	Vmeas_rising		
		D_overshoot_time	Vmeas_falling		
		Pulse_high	Rref_diff		
		Pulse_low	Cref_diff		
		Pulse_time			
		V_meas			
[Submodel] SUBPARAMETER					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
		Submodel_type			
Submodel_type SELECTIONS					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
		Dynamic_clamp	Fall_back		
		Bus_hold			
[Submodel Spec] SUBPARAMETERS					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
		V_trigger_r			
		V_trigger_f			
		Off_delay			
Test_data_type and Test_load_type SELECTIONS					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
			Single_ended		
			Differential		
[Begin EMI Component] KEYWORDS					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
				[Pin EMI]	
				[Pin Domain EMI]	
Model_emi_type SELECTIONS					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
				Ferrite	
				Not_a_Ferrite	
(SUBPARAMETERS) FOR OTHER KEYWORDS					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
[Component]		[Component] (Si_location, Timing_location)		[Begin EMI Component] (Domain, Cpd, C_Heatsink_gnd, C_Heatsink_float)	[Repeater Pin] (tx_non_inv_pin) [Initial Delay] (V-T, I- T)*
[Package] (R_pkg, L_pkg, C_pkg)				[Pin EMI] (domain_name, clock_div)	
[Pin] (signal_name, model_name, R_pin,				[Pin Domain EMI] (percentage)	

L_pin, C_pin)					
	[Pin Mapping] (pulldown_ref, pullup_ref, gnd_clamp_ref, power_clamp_ref)		[Pin Mapping] (ext_ref)	[Begin EMI Model] (Model_emi_type, Model_Domain)	
	[Diff Pin] (inv_pin, vdiff, t_delay, tdelay_min, tdelay_max)			[Algorithmic Model] (Executable)	[Algorithmic Model] (Executable_Rx*, Executable_Tx*)
		[Series Pin Mapping] (pin_2, model_name, function_table_group)		[C Comp Corner] (C_comp, C_comp_pullup, C_comp_pulldown, C_comp_power_clamp , C_comp_gnd_clamp	
		[Series Switch Groups] (On, Off)			
			[Circuit Call] (Signal_pin, Diff_signal_pins, Series_pins, Port_map)		
			[Receiver Thresholds] (Vth, Vth_min, Vth_max, Vinh_ac,Vinh_dc, Vinl_ac, Vinl_dc, Threshold_sensitivity, Reference_supply, Vcross_low, V_cross_high, Vdiff_ac, Vdiff_dc, Tslew_ac, Tdiffslew_ac)		
		[Series MOSFET] (Vds)			
[Ramp] (dV/dt_r, dV/dt_f)	[Ramp] (R_load)				
	[Rising Waveform] (R_fixture, V_fixture, V_fixture_min, V_fixture_max, C_fixture, L_fixture, R_dut, L_dut, C_dut)				
	[Falling Waveform] (R_fixture, V_fixture, V_fixture_min, V_fixture_max, C_fixture, L_fixture, R_dut, L_dut, C_dut)				
			[Test Data] (Test_data_type, Driver_model, Driver_model_inv, Test_load) (moved to top-level in 5.1)		
			[Test Load] (Test_load_type, C1_near, Rs_near, Ls_near, C2_near, Rpl_near, Rp2_near, Td, Zo, Rpl_far, Rp2_far, C1_far, Ls_far, Rs_far, V_term1, V_term2, Receiver_model, Receiver_model_inv, R_diff_near, R_diff_far) (moved to top-level in 5.1)		
			[External Model] (Language, Corner,		[External Model] (Converter_Parameters

			Parameters, Ports, D_to_A, A_to_D)		)
			[External Circuit] (Language, Corner, Parameters, Ports, D_to_A, A_to_D)		[External Circuit] (Converter_Parameters)
	[Pin Numbers]	[Pin Numbers] (Len, L, C, R, Fork, Endfork)			
	[Resistance Matrix] (Banded_matrix, Sparse_matrix, Full_matrix)				
	[Inductance Matrix] (Banded_matrix, Sparse_matrix, Full_matrix)				
	[Capacitance Matrix] (Banded_matrix, Sparse_matrix, Full_matrix)				
		[Pin List] (signal_name)			
		[Begin Board Description] (Len, L, C, R, Fork, Endfork, Node, Pin)			
OTHER NOTABLE CHANGES					
Version 1.1	Version 2.1	Version 3.2	Version 4.2	Version 5.1	Version 6.0/6.1*
File width = 80			File width=120		
Filename length = 8		Filename length = 20	Filename length = 40		
Model name length = 20			Model name length = 40		
		Submodel name length = 20	Submodel name length = 40		
	[Rising Waveform], [Falling Waveform] rows = 100		[Rising Waveform], [Falling Waveform] rows = 1000		
Vinh, Vinl optional for Input and I/O	Vinh, Vinl required for Input and I/O				
Reserved words NC POWER, GND, NA			Added reserved word CIRCUITCALL		
Fixed keyword space and underbar convention	Space and underbar equivalent in keywords				
Original comment characters	+, - removed as comment characters				
Multipliers M, k, m, u, n, p	Multipliers T, G and f added				
Buffers by extraction		By construction added	By language linkage added	EMI, SSO, and Algorithmic Modeling Interface added, [Test Load] and [Test Data] hierarchy changed	PAM4 mapping and other IBIS-AMI parameters